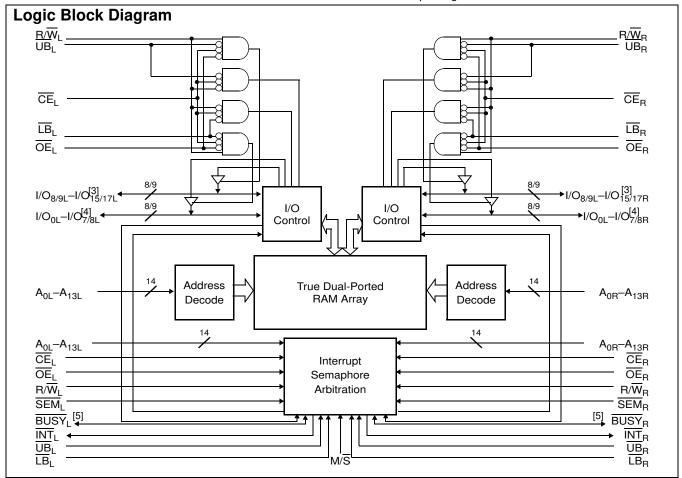


16K x 16/18 Dual-Port Static RAM

Features

- True dual-ported memory cells that allow simultaneous access of the same memory location
- 16K x 16 organization (CY7C026A/026B^[1])
- 16K x 18 organization (CY7C036A)
- 0.35 micron CMOS for optimum speed and power
- High speed access: 12^[2], 15, and 20 ns
- Low operating power
- Active: I_{CC} = 180 mA (typical)
- Standby: I_{SB3} = 0.05 mA (typical)
- Fully asynchronous operation

- Automatic power down
- Expandable data bus to 32/36 bits or more using Master/Slave chip select when using more than one device
- On-chip arbitration logic
- Semaphores included to permit software handshaking between ports
- INT flags for port-to-port communication
- Separate upper-byte and lower-byte control
- Pin select for Master or Slave
- Commercial and Industrial temperature ranges
- Available in 100-Pin TQFP
- Pb-free packages available



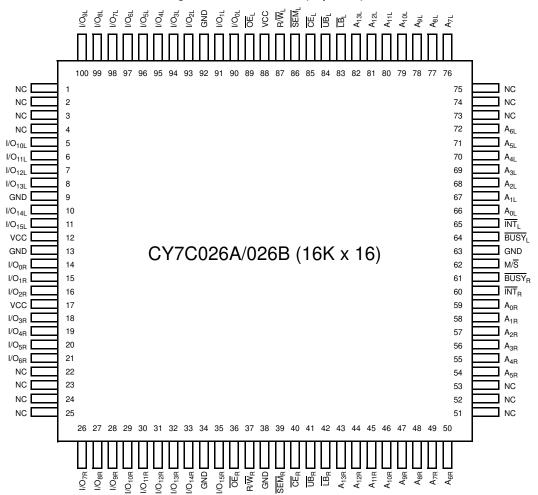
Notes

- 1. CY7C026A and CY7C026B are functionally identical.
- See page 6 for Load Conditions.
- I/O_8 – I/O_{15} for x16 devices; I/O_9 – I/O_{17} for x18 devices.
- | I/O₀-I/O₇ for x16 devices; I/O₀-I/O₈ for x18 devices.
 | BUSY is an output in master mode and an input in slave mode.



Pin Configurations

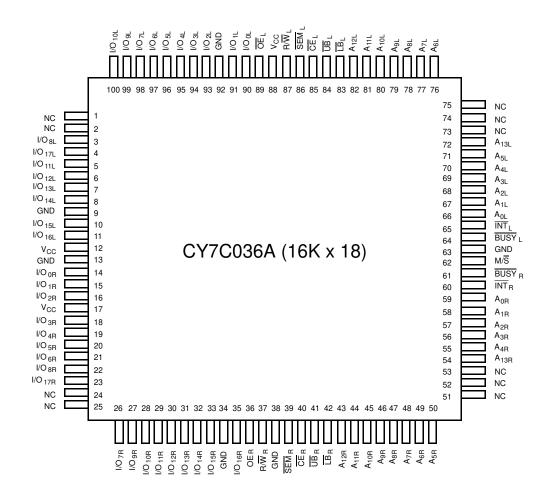
Figure 1. 100-Pin TQFP (Top View)





Pin Configurations (continued)

Figure 2. 100-Pin TQFP (Top View)



Selection Guide

Parameter	CY7C026A/026B CY7C036A -12 ^[2]	CY7C026A/026B CY7C036A -15	CY7C026A/026B CY7C036A -20	Unit
Maximum Access Time	12	15	20	ns
Typical Operating Current	195	190	180	mA
Typical Standby Current for I _{SB1} (Both Ports TTL Level)	55	50	45	mA
Typical Standby Current for I _{SB3} (Both Ports CMOS Level)	0.05	0.05	0.05	mA



Pin Definitions

Left Port	Right Port	Description
CE _L	CE _R	Chip Enable
R/\overline{W}_L	R/W _R	Read/Write Enable
OE _L	OE _R	Output Enable
A _{0L} -A _{13L}	A _{0R} -A _{13R}	Address
I/O _{0L} –I/O _{17L}	I/O _{0R} –I/O _{17R}	Data Bus Input/Output
SEM _L	SEM _R	Semaphore Enable
UB _L	UB _R	Upper Byte Select (I/O ₈ –I/O ₁₅ for x16 devices; I/O ₉ –I/O ₁₇ for x18 devices)
LB _L	LB _R	Lower Byte Select (I/O ₀ –I/O ₇ for x16 devices; I/O ₀ –I/O ₈ for x18 devices)
INT _L	INT _R	Interrupt Flag
BUSY _L	BUSY _R	Busy Flag
M/S		Master or Slave Select
V _{CC}		Power
GND		Ground
NC		No Connect

Architecture

The CY7C026A/026B and CY7C036A consist of an array of 16K words of 16 and 18 bits each of <u>dual-port</u> RAM cells, I/O and address lines, and control signals (CE, OE, R/W). These control pins permit independent access for reads or writes to any location in memory. To handle simultaneous writes/reads to the same location, a BUSY pin is provided on each port. Two Interrupt (INT) pins can be <u>utilized</u> for port-to-port communication. Two Semaphore (SEM) control pins are used for allocating shared resources. With the M/S pin, the devices can function as a master (BUSY pins are outputs) or as a slave (BUSY pins are inputs). The devices also have an automatic power down feature controlled by CE. Each port is provided with its own Output Enable control (OE), which allows data to be read from the device.

Functional Description

The CY7C026A/026B and CY7C036A are low power CMOS 16K x 16/18 dual-port static RAMs. Various arbitration schemes are included on the devices to handle situations when multiple processors access the same piece of data. Two ports are provided, permitting independent, asynchronous access for reads and writes to any location in memory. The devices can be utilized as standalone 16/18-bit dual-port static RAMs or multiple devices can be combined to function as <u>a</u> 32/36-bit or wider master/slave dual-port static RAM. An M/S pin is provided for implementing 32/36-bit or wider memory applications without the need for separate master and slave devices or additional discrete logic. Application areas include interprocessor/multiprocessor designs, communications status buffering, and dual-port video/graphics memory.

Each port has independent control pins: Chip Enable (CE), Read or Write Enable (R/W), and Output Enable (OE). Two flags are provided on each port (BUSY and INT). BUSY signals that the port is trying to access the same location currently being accessed by the other port. The Interrupt flag (INT) permits

communication between ports or systems by means of a mail box. The semaphores are used to pass a flag, or token, from one port to the other to indicate that a shared resource is in use. The semaphore logic is comprised of eight shared latches. Only one side can control the latch (semaphore) at any time. Control of a semaphore indicates that a shared resource is in use. An automatic power down feature is controlled independently on each port by the chip enable pin.

The CY7C026A/026B and CY7C036A are available in 100-pin Thin Quad Plastic Flatpack (TQFP) packages.

Write Operation

Data must be set up for a duration of t_{SD} before the <u>ris</u>ing edge of R/W to either the R/W pin (see Figure 8) or the CE pin (see Figure 9). Required inputs for non-contention operations are summarized in Table 1.

If a location is being written to by one port and the opposite port attempts to read that location, a port-to-port flowthrough delay must occur before the data is read on the output; otherwise the data read is not deterministic. Data is valid on the port t_{DDD} after the data is presented on the other port.

Read Operation

Interrupts

The upper two memory locations may be used for message passing. The highest memory location (3FFF) is the mailbox for the right port and the second highest memory location (3FFE) is the mailbox for the left port. When one port writes to the other port's mailbox, an interrupt is generated to the owner. The interrupt is reset when the owner reads the contents of the mailbox. The message is user defined.



Each port can read the other port's mailbox without resetting the interrupt. The active state of the busy signal (to a port) prevents the port from setting the interrupt to the winning port. Also, an active busy to a port prevents that port from reading its own mailbox and, thus, resetting the interrupt to it.

If an application does not require message passing, do not connect the interrupt pin to the processor's interrupt request input pin.

The operation of the interrupts and their interaction with Busy are summarized in Table 2.

Busy

The CY7C026A/026B and CY7C036A provide on-chip arbitration to resolve simultaneous memory location access (contention). If both ports' CEs are asserted and an address match occurs within t_{PS} of each other, the busy logic determines which port has access. If t_{PS} is violated, one port definitely gains permission to the <u>location</u>, but it is not predictable which port gets that permission. BUSY is asserted t_{BLA} after an address match or t_{BLC} after CE is taken LOW.

Master/Slave

A M/S pin is provided to expand the word width by configuring the device as either a master or a slave. The BUSY output of the master is connected to the BUSY input of the slave. This allows the device to interface to a master device with no external components. Writing to slave devices must be delayed until after the BUSY input has settled (t_{BLC} or t_{BLA}), otherwise, the slave chip may begin a write cycle during a contention situation. When tied HIGH, the M/S pin allows the device to be used as a master and, therefore, the BUSY line is an output. BUSY can then be used to send the arbitration outcome to a slave.

Semaphore Operation

The CY7C026A/026B and CY7C036A provide eight semaphore latches, which are separate from the dual-port memory locations. Semaphores are used to reserve resources that are shared between the two ports. The state of the semaphore indicates that

a resource is in use. For example, if the left port wants to request a given resource, it sets a latch by writing a zero to a semaphore location. The left port then verifies its success in setting the latch by reading it. After writing to the semaphore, $\overline{\text{SEM}}$ or $\overline{\text{OE}}$ must be deasserted for t_{SOP} before attempting to read the semaphore. The semaphore value is available $t_{\text{SWRD}}+t_{\text{DOE}}$ after the rising edge of the semaphore write. If the left port was successful (reads a zero), it assumes control of the shared resource, otherwise (reads a one) it assumes the right port has control and continues to poll the semaphore. When the right side has relinquished control of the semaphore (by writing a one), the left side succeeds in gaining control of the semaphore. If the left side no longer requires the semaphore, a one is written to cancel its request.

Semaphores are accessed by asserting \overline{SEM} LOW. The \overline{SEM} pin functions as a chip select for the semaphore latches (\overline{CE} must remain HIGH during \overline{SEM} LOW). A₀₋₂ represents the semaphore address. \overline{OE} and R/W are used in the same manner as a normal memory access. When writing or reading a semaphore, the other address pins have no effect.

When writing to the semaphore, only I/O_0 is used. If a zero is written to the left port of an available semaphore, a one appears at the same semaphore address on the right port. That semaphore can now only be modified by the side showing zero (the left port in this case). If the left port now relinquishes control by writing a one to the semaphore, the semaphore is set to one for both sides. However, if the right port had requested the semaphore (written a zero) while the left port had control, the right port would immediately own the semaphore as soon as the left port released it. Table 3 shows sample semaphore operations.

When reading a semaphore, all sixteen/eighteen data lines output the semaphore value. The read value is latched in an output register to prevent the semaphore from changing state during a write from the other port. If both ports attempt to access the semaphore within $t_{\rm SPS}$ of each other, the semaphore is definitely obtained by one side or the other, but there is no quarantee which side controls the semaphore.



Maximum Ratings^[6]

Exceeding maximum ratings may shorten the useful life of the device. User guidelines are not tested.

Storage Temperature-65°C to +150°C Ambient Temperature with Power Applied55°C to +125°C

DC Voltage Applied to Outputs

in High Z State-0.5V to +7.0V

Supply Voltage to Ground Potential.....-0.3V to +7.0V

DC Input Voltage ^[7]	0.5V to + 7.0V
Output Current into Outputs (LOW)	20 mA
Static Discharge Voltage	>2001V
Latch Up Current	>200 mA

Operating Range

Range	Ambient Temperature	V _{cc}
Commercial	0°C to +70°C	5V ± 10%
Industrial	-40°C to +85°C	5V ± 10%

Electrical Characteristics Over the Operating Range

_		D					C026A/ Y7C036					
Parameter	Description	Description		-12 ^[2]			-15		-20			Unit
			Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	
V _{OH}	Output HIGH Voltage (V _{CC} = Min., I _{OH} = -4.0 mA)		2.4			2.4			2.4			V
V _{OL}	Output LOW Voltage (V _{CC} = Min., I _{OH} = +4.0 mA)				0.4			0.4			0.4	V
V _{IH}	Input HIGH Voltage		2.2			2.2			2.2			V
V _{IL}	Input LOW Voltage				8.0			0.8			0.8	V
I _{OZ}	Output Leakage Current		-10		10	-10		10	-10		10	μΑ
I _{CC}	Operating Current (V _{CC} = Max,	Com'l.		195	325		190	285		180	275	mA
	I _{OUT} = 0 mA) Outputs Disabled	Indust.					215	305				mA
I _{SB1}	Standby Current	Com'l.		55	75		50	70		45	65	mA
	(Both Ports TTL Level) $CE_L \& CE_R \ge V_{IH}, f = f_{MAX}$	Indust.					65	95				mA
I _{SB2}	Standby Current	Com'l.		125	205		120	180		110	160	mA
	$\frac{(One\ Port\ TTL\ Level)}{CE_L\ \ CE_R \ge V_{IH},\ f=f_{MAX}}$	Indust.					135	205				mA
I _{SB3}	Standby Current	Com'l.		0.05	0.5		0.05	0.5		0.05	0.5	mA
	$\frac{\text{(Both Ports CMOS Level)}}{\text{CE}_L \& \text{CE}_R \ge \text{V}_{\text{CC}} - 0.2\text{V}, \text{ f} = 0}$	Indust.					0.05	0.5				mA
I _{SB4}	Standby Current Com'l.			115	185		110	160		100	140	mA
	$\frac{(One\ Port\ CMOS\ Level)}{CE_L\ \ CE_R \ge V_{IH},\ f=f_{MAX}^{[8]}}$	Indust.					125	175		_		mA

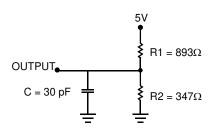
Capacitance^[9]

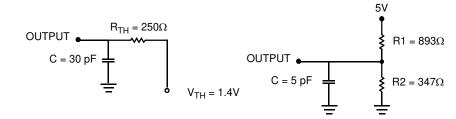
Parameter	Description	Test Conditions	Max	Unit
C _{IN}	Input Capacitance	$T_A = 25^{\circ}C, f = 1 \text{ MHz},$	10	pF
C _{OUT}	Output Capacitance	$V_{CC} = 5.0V$	10	pF

- 6. The voltage on any input or I/O pin cannot exceed the power pin during power up.7. Pulse width < 20 ns.
- 8. f_{MAX} = 1/t_{RC} = All inputs cycling at f = 1/t_{RC} (except output enable). f = 0 means no address or control lines change. This applies only to inputs at CMOS level standby I_{SB3}.
 9. Tested initially and after any design or process changes that may affect these parameters.



Figure 3. AC Test Loads and Waveforms



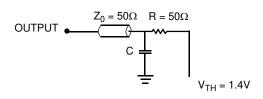


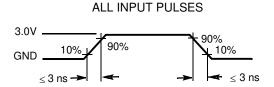
(a) Normal Load (Load 1)

(b) Thévenin Equivalent (Load 1)

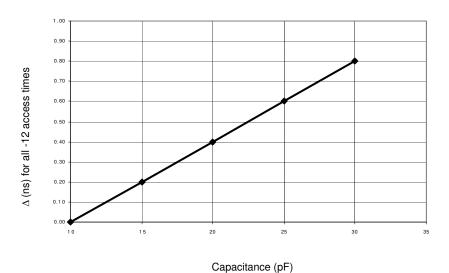
(c) Three-State Delay (Load 2) (Used for t_{LZ}, t_{HZ}, t_{HZWE}, & t_{LZWE} including scope and jig)

Figure 4. AC Test Loads (Applicable to -12 only)^[10]





(a) Load 1 (-12 only)



(b) Load Derating Curve

Note 10. Test Conditions: C = 10 pF.



Switching Characteristics Over the Operating Range^[11]

_			CY7C026A/026B CY7C036A							
Parameter	Description	-1	2 ^[2]	-	15	-:	20	Unit		
		Min	Max	Min	Max	Min	Max			
READ CYCLE										
t _{RC}	Read Cycle Time	12		15		20		ns		
t _{AA}	Address to Data Valid		12		15		20	ns		
t _{OHA}	Output Hold From Address Change	3		3		3		ns		
t _{ACE} ^[12]	CE LOW to Data Valid		12		15		20	ns		
t _{DOE}	OE LOW to Data Valid		8		10		12	ns		
t _{LZOE} [13, 14, 15]	OE LOW to Low Z	3		3		3		ns		
t _{HZOE} [13, 14, 15]	OE HIGH to High Z		10		10		12	ns		
t _{LZCE} [13, 14, 15]	CE LOW to Low Z	3		3		3		ns		
t _{HZCE} ^[13, 14, 15]	CE HIGH to High Z		10		10		12	ns		
t _{PU} ^[15]	CE LOW to Power Up	0		0		0		ns		
t _{PD} ^[15]	CE HIGH to Power Down		12		15		20	ns		
t _{ABE} ^[12]	Byte Enable Access Time		12		15		20	ns		
WRITE CYCLE					l .		l .			
t _{WC}	Write Cycle Time	12		15		20		ns		
t _{SCE} ^[12]	CE LOW to Write End	10		12		15		ns		
t _{AW}	Address Valid to Write End	10		12		15		ns		
t _{HA}	Address Hold From Write End	0		0		0		ns		
t _{SA} ^[12]	Address Setup to Write Start	0		0		0		ns		
t _{PWE}	Write Pulse Width	10		12		15		ns		
t _{SD}	Data Setup to Write End	10		10		15		ns		
t _{HD} ^[17]	Data Hold From Write End	0		0		0		ns		
t _{HZWE} [14, 15]	R/W LOW to High Z		10		10		12	ns		
t _{LZWE} [14, 15]	R/W HIGH to Low Z	3		3		3		ns		
t _{WDD} ^[16]	Write Pulse to Data Delay		25		30		45	ns		
t _{DDD} ^[16]	Write Data Valid to Read Data Valid		20		25		30	ns		

^{11.} Test conditions assume signal transition time of 3 ns or less, timing reference levels of 1.5V, input pulse levels of 0 to 3.0V, and output loading of the specified $I_{O/}I_{OH}$ and 30 pF load capacitance.

12. To access RAM, $\overline{CE} = L$, $\overline{UB} = L$, $\overline{SEM} = H$. To access semaphore, $\overline{CE} = H$ and $\overline{SEM} = L$. Either condition must be valid for the entire t_{SCE} time.

13. At any given temperature and voltage condition for any given device, t_{HZCE} is less than t_{LZCE} and t_{HZOE} is less than t_{LZOE} .

^{14.} Test conditions used are Load 3.

^{15.} This parameter is guaranteed but not tested.

^{16.} For information on port-to-port delay through RAM cells from writing port to reading port, refer to Figure 12. 17. For 15 ns industrial parts t_{HD} minimum is 0.5 ns.



Switching Characteristics Over the Operating Range^[11] (continued)

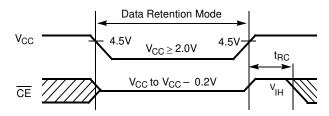
_					6A/026B 036A			
Parameter	Description	-1	2 ^[2]	-	-15		20	Unit
		Min	Max	Min	Max	Min	Max	
BUSY TIMING[18]	•						
t _{BLA}	BUSY LOW from Address Match		12		15		20	ns
t _{BHA}	BUSY HIGH from Address Mismatch		12		15		20	ns
t _{BLC}	BUSY LOW from CE LOW		12		15		20	ns
t _{BHC}	BUSY HIGH from CE HIGH		12		15		17	ns
t _{PS}	Port Setup for Priority	5		5		5		ns
t _{WB}	R/W HIGH after BUSY (Slave)	0		0		0		ns
t _{WH}	R/W HIGH after BUSY HIGH (Slave)	11		13		15		ns
t _{BDD} ^[19]	BUSY HIGH to Data Valid		12		15		20	ns
INTERRUPT TI	MING ^[18]		•	•	•	•	•	•
t _{INS}	INT Set Time		12		15		20	ns
t _{INR}	INT Reset Time		12		15		20	ns
SEMAPHORE	TIMING							
t _{SOP}	SEM Flag Update Pulse (OE or SEM)	10		10		10		ns
t _{SWRD}	SEM Flag Write to Read Time	5		5		5		ns
t _{SPS}	SEM Flag Contention Window	5		5		5		ns
t _{SAA}	SEM Address Access Time		12		15		20	ns

Data Retention Mode

The CY7C026A/026B and CY7C036A are designed with battery backup in mind. Data retention voltage and supply current are guaranteed over temperature. The following rules ensure data retention:

- 1. Chip Enable (CE) must be held HIGH during data retention, within V_{CC} to $V_{CC} - 0.2V$.
- 2. $\overline{\text{CE}}$ must be kept between $V_{CC} 0.2V$ and 70% of V_{CC} during the power up and power down transitions.
- 3. The RAM can begin operation >t $_{RC}$ after V_{CC} reaches the minimum operating voltage (4.5 volts).

Timing



Parameter	Test Conditions ^[20]	Max	Unit
ICC _{DR1}	At VCC _{DR} = 2V	1.5	mA

- 18. Test conditions used are Load 2.
- 19. t_{BDD} is a calculated parameter and is the greater of t_{WDD} – t_{PWE} (actual) or t_{DDD} – t_{SD} (actual). 20. $CE = V_{CC}$, $V_{in} = GND$ to V_{CC} , $T_A = 25^{\circ}C$. This parameter is guaranteed but not tested.



Switching Waveforms

Figure 5. Read Cycle No.1 (Either Port Address Access)[21, 22, 23]

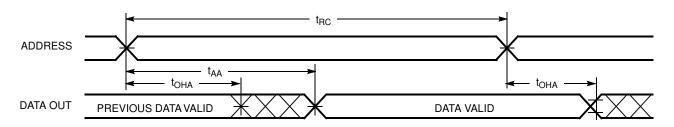


Figure 6. Read Cycle No.2 (Either Port CE/OE Access)[21, 24, 25]

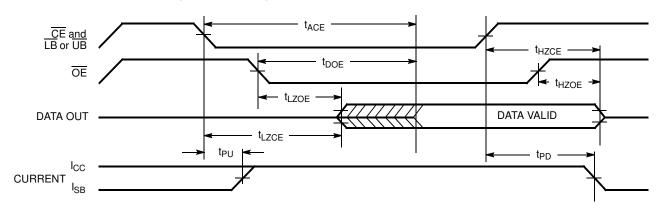
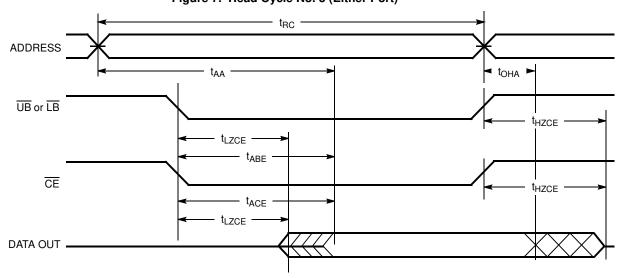


Figure 7. Read Cycle No. 3 (Either Port) [21, 23, 24, 25]



- 21. R/W is HIGH for read cycles.

 22. <u>Device</u> is continuously selected $\overline{CE} = V_{|L}$ and \overline{UB} or $\overline{LB} = V_{|L}$. This waveform cannot be used for semaphore reads.

 23. $\overline{OE} = V_{|L}$.

- 24. Address valid prior to or coincident with $\overline{\text{CE}}$ transition LOW. 25. To access RAM, $\overline{\text{CE}} = \text{V}_{\text{IL}}$, $\overline{\text{UB}}$ or $\overline{\text{LB}} = \text{V}_{\text{IL}}$, $\overline{\text{SEM}} = \text{V}_{\text{IH}}$. To access semaphore, $\overline{\text{CE}} = \text{V}_{\text{IH}}$, $\overline{\text{SEM}} = \text{V}_{\text{IL}}$.



Figure 8. Write Cycle No. 1: R/W Controlled $Timing^{[26, 27, 28, 29]}$

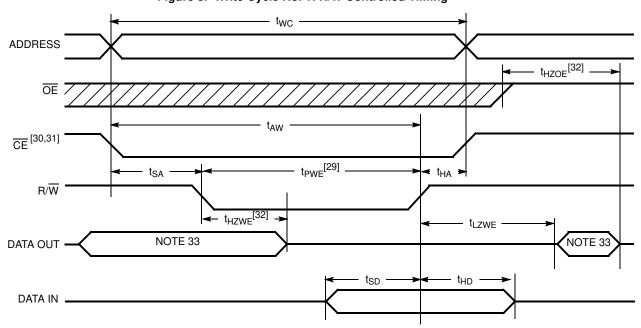
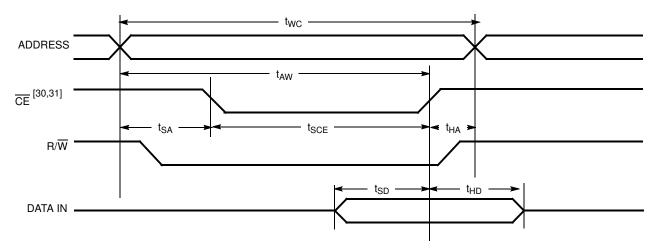


Figure 9. Write Cycle No. 2: $\overline{\text{CE}}$ Controlled Timing^[26, 27, 28, 34]



- 26. R/W must be HIGH during all address transitions.

- 26. If William occurs during all address transitions.

 27. A write occurs during the overlap (t_{SCE} or t_{PWE}) of a LOW CE or SEM and a LOW UB or LB.

 28. t_{HA} is measured from the earlier of CE or R/W or (SEM or R/W) going HIGH at the end of write cycle.

 29. If OE is LOW during a R/W controlled write cycle, the write pulse width must be the larger of t_{PWE} or (t_{HZWE} + t_{SD}) to allow the I/O drivers to turn off and data to be placed on the bus for the required t_{SD}. If OE is HIGH during an R/W controlled write cycle, this requirement does not apply and the write pulse can be as expert on the required t_{SD}. to be placed on the bus for the required t_{SD}. If OE is HIGH during an H/W controlled write cycle, this requirement does not apply and the Mino p as short as the specified t_{PWE}.

 30. To access RAM, CE = V_{IL}, SEM = V_{IH}.

 31. To access upper byte, CE = V_{IL}, UB = V_{IL}, SEM = V_{IH}.

 To access lower byte, CE = V_{IL}, LB = V_{IL}, SEM = V_{IH}.

 32. Transition is measured ±500 mV from steady state with a 5 pF load (including scope and jig). This parameter is sampled and not 100% tested.

 33. During this period, the I/O pins are in the output state, and input signals must not be applied.

 34. If the CE or SEM LOW transition occurs simultaneously with or after the R/W LOW transition, the outputs remain in the high impedance state.



Figure 10. Semaphore Read After Write Timing, Either Side^[35]

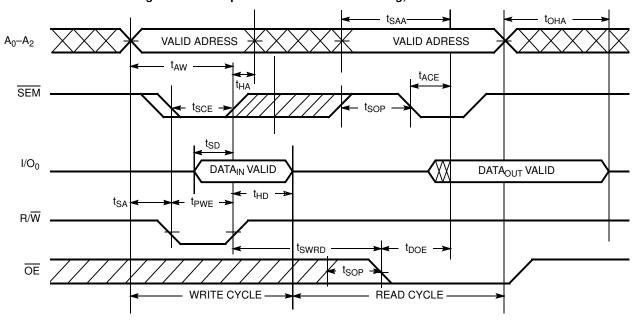
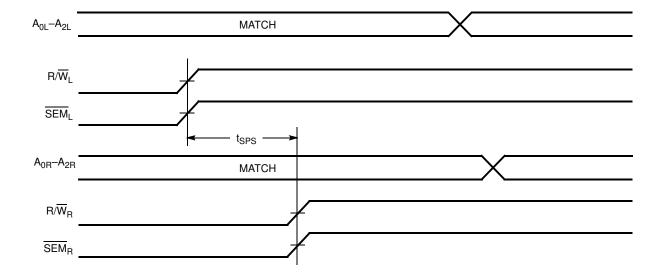


Figure 11. Timing Diagram of Semaphore Contention $^{[36,\ 37,\ 38]}$



Notes

35. CE = HIGH for the duration of the above timing (both write and read cycle).

36. I/O_{0R} = I/O_{0L} = LOW (request semaphore); CE_R = CE_L = HIGH.

37. Semaphores are reset (available to both ports) at cycle start.

38. If t_{SPS} is violated, the semaphore is definitely obtained by one side or the other, but which side gets the semaphore is unpredictable.



Figure 12. Timing Diagram of Read with \overline{BUSY} (M/ \overline{S} = HIGH)[39]

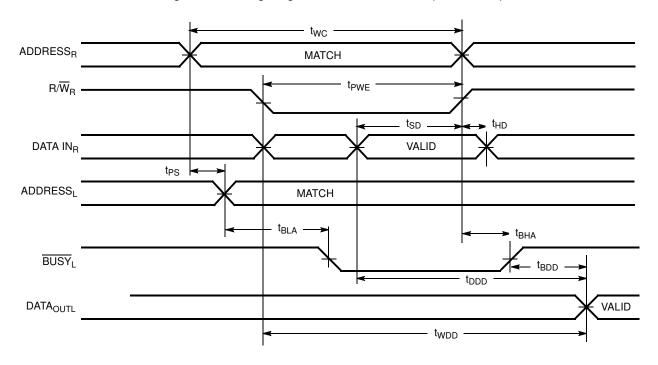


Figure 13. Write Timing with Busy Input $(M/\overline{S} = LOW)$

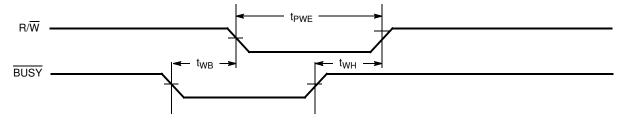




Figure 14. Busy Timing Diagram No. 1 ($\overline{\text{CE}}$ Arbitration)[40]

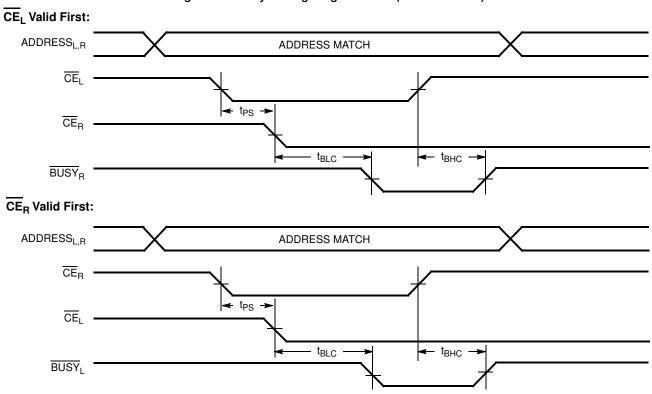
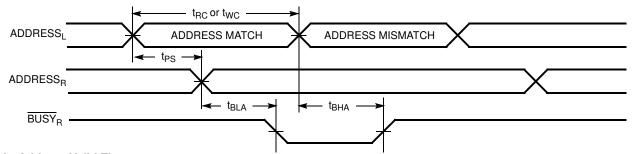
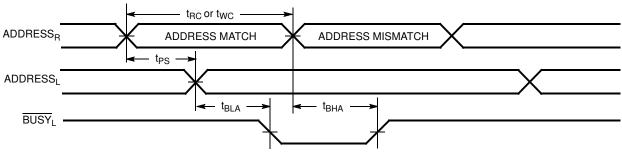


Figure 15. Busy Timing Diagram No. 2 (Address Arbitration)^[40]

Left Address Valid First:



Right Address Valid First:



Note

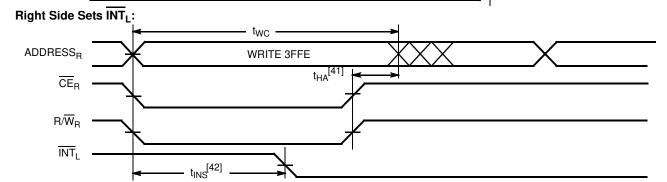
40. If t_{PS} is violated, the busy signal is asserted on one side or the other, but there is no guarantee to which side BUSY is asserted.

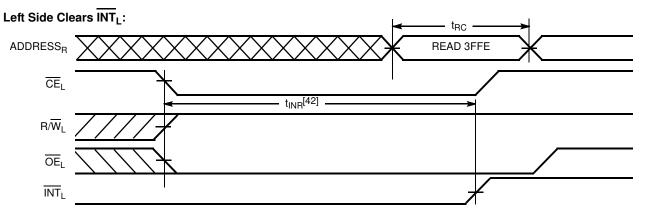


 $\overline{\mathsf{INT}}_\mathsf{R}$

Switching Waveforms (continued)

Figure 16. Interrupt Timing Diagrams Left Side Sets INT_R: twc ADDRESS_I WRITE 3FFF t_{HA}[41] $\overline{\mathsf{CE}}_\mathsf{L}$ R/\overline{W}_L $\overline{\mathsf{INT}}_\mathsf{R}$ - t_{INS}[42] Right Side Clears INT_R: t_{RC} ADDRESS_R **READ 3FFF** $\overline{\text{CE}}_{\text{R}}$ t_{INR}[42] R/\overline{W}_R OER





Notes

- 41. t_{HA} depends on which enable pin $(\overline{CE}_L \text{ or } R/\overline{W}_L)$ is deasserted first. 42. t_{INS} or t_{INR} depends on which enable pin $(\overline{CE}_L \text{ or } R/\overline{W}_L)$ is asserted last.



Table 1. Non-Contending Read/Write

		ln	puts			Ou	itputs	
CE	R/W	OE	UB	LB	SEM	I/O ₉ -I/O ₁₇	I/O ₀ –I/O ₈	Operation
Н	Х	Х	Х	Х	Н	High Z	High Z	Deselected: Power Down
Х	Х	Х	Н	Н	Н	High Z	High Z	Deselected: Power Down
L	L	Х	L	Н	Н	Data In	High Z	Write to Upper Byte Only
L	L	Х	Н	L	Н	High Z	Data In	Write to Lower Byte Only
L	L	Х	L	L	Н	Data In	Data In	Write to Both Bytes
L	Н	L	L	Н	Н	Data Out	High Z	Read Upper Byte Only
L	Н	L	Н	L	Н	High Z	Data Out	Read Lower Byte Only
L	Н	L	L	L	Н	Data Out	Data Out	Read Both Bytes
Х	Х	Н	Χ	Х	Х	High Z	High Z	Outputs Disabled
Н	Н	L	Х	Х	L	Data Out	Data Out	Read Data in Semaphore Flag
Х	Н	L	Н	Н	L	Data Out	Data Out	Read Data in Semaphore Flag
Н		Х	Х	Х	L	Data In	Data In	Write D _{IN0} into Semaphore Flag
Х		Х	Н	Н	L	Data In	Data In	Write D _{IN0} into Semaphore Flag
L	Х	Х	L	Х	L			Not Allowed
L	Х	Х	Х	L	L			Not Allowed

Table 2. Interrupt Operation Example (assumes $\overline{BUSY}_L = \overline{BUSY}_R = HIGH$)

	_		Le	ft Port	Right Port					
Function	R/W _L	CEL	OEL	A _{0L-13L}	INT _L	R/W _R	CER	OER	A _{0R-13R}	INT _R
Set Right INT _R Flag	L	L	Х	3FFF	Х	Х	Х	Х	Х	L ^[44]
Reset Right INT _R Flag	Х	Χ	Х	X	Х	Х	L	L	3FFF	H ^[43]
Set Left INT _L Flag	Х	Χ	Х	X	L ^[43]	L	L	Х	3FFE	Х
Reset Left INT _L Flag	Χ	L	L	3FFE	H ^[44]	Χ	Χ	Χ	Х	Х

Table 3. Semaphore Operation Example

Function	I/O ₀ -I/O ₁₇ Left	I/O ₀ –I/O ₁₇ Right	Status
No action	1	1	Semaphore free
Left port writes 0 to semaphore	0	1	Left port has semaphore token
Right port writes 0 to semaphore	0	1	No change. Right side has no write access to semaphore
Left port writes 1 to semaphore	1	0	Right port obtains semaphore token
Left port writes 0 to semaphore	1	0	No change. Left port has no write access to semaphore
Right port writes 1 to semaphore	0	1	Left port obtains semaphore token
Left port writes 1 to semaphore	1	1	Semaphore free
Right port writes 0 to semaphore	1	0	Right port has semaphore token
Right port writes 1 to semaphore	1	1	Semaphore free
Left port writes 0 to semaphore	0	1	Left port has semaphore token
Left port writes 1 to semaphore	1	1	Semaphore free



Ordering Information

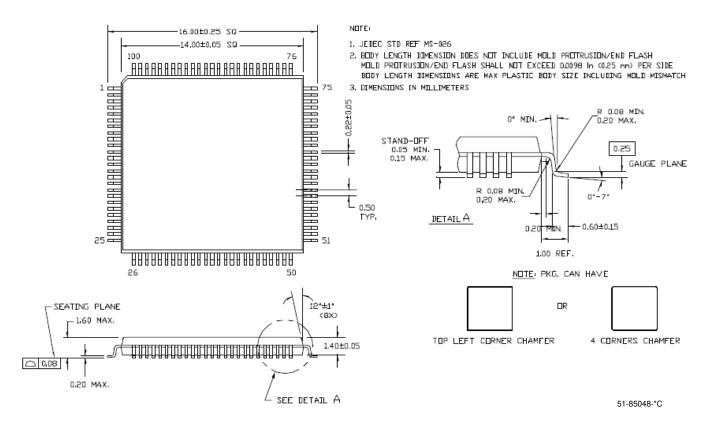
16K x16 Asynchronous Dual-Port SRAM

Speed (ns)	Ordering Code	Package Name	Package Type	Operating Range
12 ^[2]	CY7C026A-12AC	A100	100-Pin Thin Quad Flat Pack	Commercial
15	CY7C026A-15AC	A100	100-Pin Thin Quad Flat Pack	Commercial
	CY7C026A-15AXC	A100	100-Pin Pb-Free Thin Quad Flat Pack	
	CY7C026B-15AI	A100	100-Pin Thin Quad Flat Pack	Industrial
	CY7C026A-15AXI	A100	100-Pin Pb-Free Thin Quad Flat Pack	
20	CY7C026A-20AC	A100	100-Pin Thin Quad Flat Pack	Commercial
	CY7C026A-20AXC	A100	100-Pin Pb-Free Thin Quad Flat Pack	

Speed (ns)	Ordering Code	Package Name	Package Type	Operating Range
12 ^[2]	CY7C036A-12AC	A100	100-Pin Thin Quad Flat Pack	Commercial
15	CY7C036A-15AC	A100	100-Pin Thin Quad Flat Pack	Commercial
	CY7C036A-15AI	A100	100-Pin Thin Quad Flat Pack	Industrial
20	CY7C036A-20AC	A100	100-Pin Thin Quad Flat Pack	Commercial

Package Diagram

Figure 17. 100-Pin Pb-Free Thin Plastic Quad Flat Pack (TQFP) A100





Document History Page

Rev.	ECN No.	Orig. of Change	Submission Date	Description of Change
**	110198	SZV	09/29/01	Change from Spec number: 38-00832 to 38-06046
*A	122296	RBI	12/27/02	Power up requirements added to Maximum Ratings Information
*B	237621	YDT	See ECN	Removed cross information from features section
*C	393454	YIM	See ECN	Added Pb-Free Logo
				Added Pb-Free parts to ordering information:
				CY7C026A-15AXC, CY7C026A-20AXC
*D	2623540	VKN/PYRS		Added CY7C026B part Added CY7C026A-15AXI part in the Ordering Information table

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Revised December 10, 2008

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